KP-3216EC

3.2 x 1.6 mm SMD Chip LED Lamp



• The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode

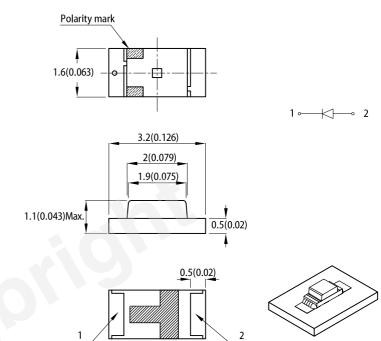
FEATURES

- 3.2 mm x 1.6 mm SMD LED, 1.1 mm thickness
- Low power consumption
- Wide viewing angle
- · Ideal for backlight and indicator
- Package: 2000 pcs / reel
- Moisture sensitivity level: 3
- Halogen-free
- RoHS compliant

APPLICATIONS

- Backlight
- Status indicator
- · Home and smart appliances
- Wearable and portable devices
- · Healthcare applications

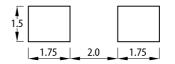
PACKAGE DIMENSIONS



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RECOMMENDED SOLDERING PATTERN

(units : mm; tolerance : \pm 0.1)



Notes

Notes: 1. All dimensions are in millimeters (inches). 2. Tolerance is ±0.2(0.008') unless otherwise noted. 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

The device has a single mounting surface. The device must be mounted according to the specifications.

SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	lv (mcd) @ 20mA ^[2]		Viewing Angle ^[1]	
r art Number			Min.	Тур.	201/2	
KP-3216EC	 High Efficiency Red (GaAsP/GaP) 	Water Clear	8	15	160°	
			*3	*8	100	

Notes

1. 61/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 2. Luminous intensity / luminous flux: +/-15%.
 * Luminous intensity value is traceable to CIE127-2007 standards.

ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Cumula al	Emitting Color	Value		11
Parameter	Symbol	Emitting Color	Тур.	Max.	Unit
Wavelength at Peak Emission I _F = 20mA	λ_{peak}	High Efficiency Red	627	-	nm
Dominant Wavelength I _F = 20mA	λ _{dom} ^[1]	High Efficiency Red	617	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 20mA	Δλ	High Efficiency Red	45	-	nm
Capacitance	С	High Efficiency Red	15	-	pF
Forward Voltage I _F = 20mA	V _F ^[2]	High Efficiency Red	2	2.5	V
Reverse Current (V_R = 5V)	I _R	High Efficiency Red	-	10	μΑ
Temperature Coefficient of λ_{peak} I_F = 20mA, -10°C \leq T \leq 85°C	TC _{λpeak}	High Efficiency Red	0.13	-	nm/°C
Temperature Coefficient of λ_{dom} I_F = 20mA, -10°C \leq T \leq 85°C	TC _{λdom}	High Efficiency Red	0.06	-	nm/°C
Temperature Coefficient of $~V_F$ I_F = 20mA, -10 $^{\circ}C \leq T \leq 85 ^{\circ}C$	TCv	High Efficiency Red	-1.9	-	mV/°C

Notes

Notes: 1. The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd : ±1nm.) 2. Forward voltage: ±0.1V. 3. Wavelength value is traceable to CIE127-2007 standards. 4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

ABSOLUTE MAXIMUM RATINGS at T_A=25°C

Parameter	Symbol	Value	Unit
Power Dissipation	P _D	75	mW
Reverse Voltage	V _R	5	V
Junction Temperature	Tj	125	°C
Operating Temperature	T _{op}	-40 to +85	°C
Storage Temperature	T _{stg}	-40 to +85	°C
DC Forward Current	I _F	30	mA
Peak Forward Current	۱ _{FM} ^[1]	160	mA
Electrostatic Discharge Threshold (HBM)	-	8000	V
Thermal Resistance (Junction / Ambient)	$R_{th\ JA}^{\ [2]}$	760	°C/W
Thermal Resistance (Junction / Solder point)	$R_{th}\;{}_{JS}\;{}^{[2]}$	600	°C/W

Notes: 1. 1/10 Duty Cycle, 0.1ms Pulse Width. 2. R_{th JA}, R_{th JS} Results from mounting on PC board FR4 (pad size ≥ 16 mm² per pad). 3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

Forward Current vs. Forward Voltage

T_a = 25 °C

50

40

20

10

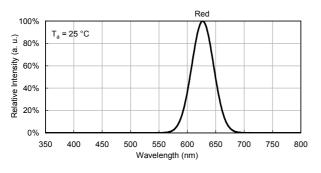
0

1.5 1.7 1.9 2.1 2.3

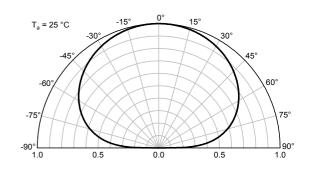
Forward current (mA) 30

TECHNICAL DATA

RELATIVE INTENSITY vs. WAVELENGTH



SPATIAL DISTRIBUTION



HIGH EFFICIENCY RED

Luminous Intensity vs. Forward Current

Forward current (mA)

T_a = 25 °C

2.5

2.0

1.5

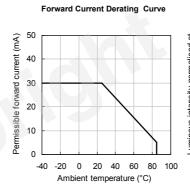
1.0

0.5

0.0

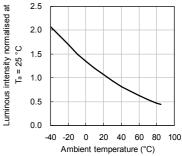
0 10 20 30 40 50

Luminous intensity normalised at 20 mA



Luminous Intensity vs. Ambient Temperature

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REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS

Forward voltage (V)

2.5

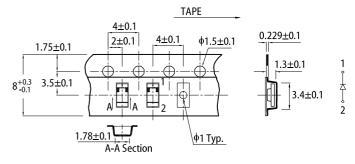
300 above 255°C (°C) 260°C max. 30s max. 10s max. 250 3°C/s max. 6°C/s max. 200 150 Temperature pre-heating 100 150~200°C above 217°C 60~120s 60~150s 50 25℃ 0 50 100 150 200 250 0 300 (sec)

Notes

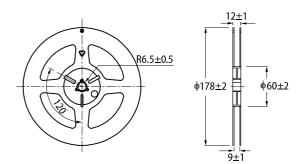
- Notes: 1. Don't cause stress to the LEDs while it is exposed to high temperature. 2. The maximum number of reflow soldering passes is 2 times. 3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

Time -

TAPE SPECIFICATIONS (units : mm)

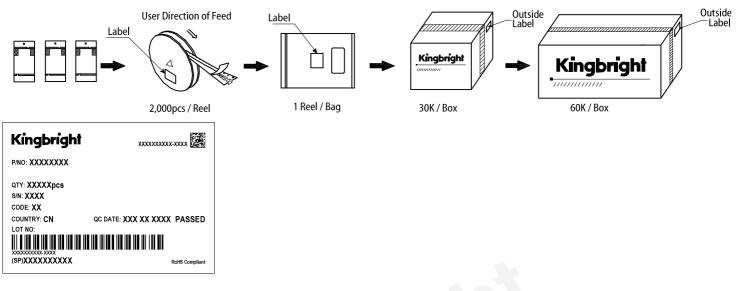


REEL DIMENSION (units : mm)



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PRECAUTIONARY NOTES

- The information included in this document reflects representative usage scenarios and is intended for technical reference only.
 The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
 When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If
- customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues. The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening
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